



## Final Product Change Notification

202108007F01 : VSSOP8 Assembly Transfer from Hana to ASEN and Test Transfer from ATBK to ASEN

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Sep 24, 2021 **Effective date:** Dec 23, 2021

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### Management summary

HANA will discontinue assembly of the PCA9306DC1 and PCA9306DC1/DG. To maintain continuity of supply, ASEN has been qualified to assemble both the standard and "/DG" part types using the same "dark green" material set which consolidates both versions under one orderable part number PCA9306DC1Z. This part number reflects the use of static shield bags (SSB) for packing due to the introduction of a roughened leadframe. Final test will also move from ATBK to ASEN to consolidate the assembly/test flows.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

HANA will discontinue assembly of the PCA9306DC1 and PCA9306DC1/DG. To maintain continuity of supply, ASEN has been qualified to assemble both the standard and "/DG" part types using the same "dark green" material set which consolidates both versions under one orderable part number PCA9306DC1Z. This part number reflects the use of static shield bags (SSB) for packing due to the introduction of a roughened leadframe. Final test will also move from ATBK to ASEN to consolidate the assembly/test flows.

Note: Currently under review is a potential augmentation to the pin 1 marker (dimple) where a laser marking may be used to further enhance it's presence as a visual marker. If deemed viable the update would be implemented in a 'running' process change..

Improvements made:

Use of a roughened leadframe that will provide superior delamination performance after customer's SMT process (please note, that no delamination or Reliability returns have occurred)

A change in die attach: Hitachi EN4900GC has higher thermal conductivity than Able bond 8290 for improved heat dissipation

A change in molding compound: Hitachi CEL-8240HF16V75 has higher thermal conductivity than Nitto MP-8000CH4 for improved heat dissipation

### Reason

Due to low VSSOP8 assembly demand at HANA, assembly of the PCA9306DC1 and PCA9306DC1/DG will move to ASEN. By consolidating assembly and test at ASEN, manufacturing efficiencies are improved to ensure timely product delivery.

### Identification of Affected Products

Packing Labels

### Product Availability

### Sample Information

Samples are available upon request

### Production

Planned first shipment Dec 14, 2021

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

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## Data Sheet Revision

A new datasheet will be issued

## Disposition of Old Products

Existing inventory will be shipped until depleted

## Additional information

Self qualification: [view online](#)

## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 24, 2021.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

<b>Name</b>	Frans Voogt
<b>Position</b>	QA Engineer
<b>e-mail address</b>	<a href="mailto:frans.voogt@nxp.com">frans.voogt@nxp.com</a>

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NXP Quality Management Team.

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NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New Orderable Part#	12NC New	Product Type New	Product Description New	Product Line	Notes
PCA9306DC1,125	935283124125	PCA9306DC1	PCA9306	(V)SSOP8	SOT765-1	DOD	No	PCA9306DC1Z	935283124473	PCA9306DC1	PCA9306	BLC6	
PCA9306DC1/DG,125	935296524125	PCA9306DC1/DG	PCA9306	(V)SSOP8	SOT765-1	DOD	No	PCA9306DC1Z	935283124473	PCA9306DC1	PCA9306	BLC6	